

NCE N-Channel Enhancement Mode Power MOSFET

Description

The NCE0125Al uses advanced trench technology and design to provide excellent $R_{DS(ON)}$ with low gate charge. It can be used in a wide variety of applications.

General Features

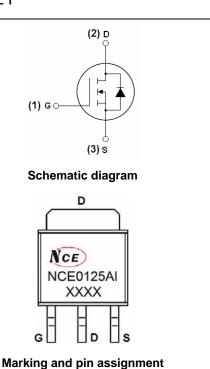
- $V_{DS} = 100V, I_D = 25A$ $R_{DS(ON)} < 36mΩ @ V_{GS} = 10V$ (Typ:31 mΩ)
- Special process technology for high ESD capability
- High density cell design for ultra low Rdson
- Fully characterized avalanche voltage and current
- Good stability and uniformity with high E_{AS}
- Excellent package for good heat dissipation

Application

- Power switching application
- Hard switched and high frequency circuits
- Uninterruptible power supply

100% UIS TESTED!

100% ΔVds TESTED!





Package Marking and Ordering Information

Device Marking	Device	Device Package	Reel Size	Tape width	Quantity
NCE0125AI	NCE0125AI	TO-251	-	-	-

Absolute Maximum Ratings (T_C=25 ℃unless otherwise noted)

Symbol	Parameter	Limit	Unit
V _{DS}	Drain-Source Voltage	100	V
V _G s	Gate-Source Voltage	±20	V
I _D	Drain Current-Continuous	25	А
I _D (100℃)	Drain Current-Continuous(TC=100℃)	17.6	Α
I _{DM}	Pulsed Drain Current	70	Α
P _D	Maximum Power Dissipation	70	W
	Derating factor	0.5	W/℃
E _{AS}	Single pulse avalanche energy (Note 5)	110	mJ
T_{J}, T_{STG}	Operating Junction and Storage Temperature Range	-55 To 175	$^{\circ}$ C



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Thermal Characteristic

R _{eJC}	Thermal Resistance, Junction-to-Case (Note 2)	2	°C/W	l
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Electrical Characteristics (T_C=25°C unless otherwise noted)

	Symbol	Parameter	Condition	Min	Тур	Max	Unit
Off Character	istics						
BV _{DSS}	Drain-Source Break	Drain-Source Breakdown Voltage		100	110	-	V
I _{DSS}	Zero Gate Voltage	Zero Gate Voltage Drain Current		-	-	1	μΑ
I _{GSS}	Gate-Body Leaka	Gate-Body Leakage Current		-	-	±100	nA
On Character	istics (Note 3)	<u> </u>					•
V _{GS(th)}	Gate Threshold	d Voltage	$V_{DS}=V_{GS}$, $I_{D}=250\mu A$	1.0	1.6	2.2	V
R _{DS(ON)}	Drain-Source On-Sta	ate Resistance	V _{GS} =10V, I _D =15A	-	31	36	mΩ
g FS	Forward Transco	onductance	V _{DS} =5V,I _D =15A	-	12	-	S
Dynamic Cha	racteristics (Note4)	1		1	Į.		
C _{lss}	Input Capac	itance		-	3000	-	PF
Coss	Output Capa	citance	V_{DS} =50V, V_{GS} =0V,	-	92	-	PF
C _{rss}	Reverse Transfer	Capacitance	F=1.0MHz	-	18.3	-	PF
Switching Ch	aracteristics (Note 4)	1		I			I.
t _{d(on)}	Turn-on Dela	y Time		-	9	-	nS
t _r	Turn-on Rise	e Time	V_{DD} =50 V , R_L =5 Ω	-	9	-	nS
$t_{d(off)}$	Turn-Off Dela	ay Time	V_{GS} =10V, R_{GEN} =3 Ω	-	31	-	nS
t _f	Turn-Off Fal	I Time		-	9	-	nS
Qg	Total Gate C	Charge)/ F0)/ OFA	-	70.4	-	nC
Q _{gs}	Gate-Source	Charge	$V_{DS}=50V, I_{D}=25A,$	-	9.0	-	nC
Q _{gd}	Gate-Drain (Charge	V _{GS} =10V	-	15.3	-	nC
Drain-Source	Diode Characteristics	1		1			
V _{SD}	Diode Forward Vo	oltage (Note 3)	V _{GS} =0V,I _S =25A	-	-	1.2	V
Is	Diode Forward Ci		-	-	-	25	Α
t _{rr}	Reverse Recov	ery Time	TJ = 25°C, IF = 25A	-	34	-	nS
Qrr	Reverse Recove	ry Charge	$di/dt = 100A/\mu s^{(Note3)}$	-	56	-	nC

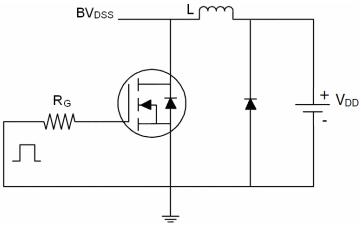
Notes:

- 1. Repetitive Rating: Pulse width limited by maximum junction temperature.
- 2. Surface Mounted on FR4 Board, $t \le 10$ sec.
- 3. Pulse Test: Pulse Width \leq 300 μ s, Duty Cycle \leq 2%.
- 4. Guaranteed by design, not subject to production
- 5. EAS Condition : Tj=25 $^{\circ}\text{C}$,VDD=50V,VG=10V,L=0.5mH,Rg=25 Ω

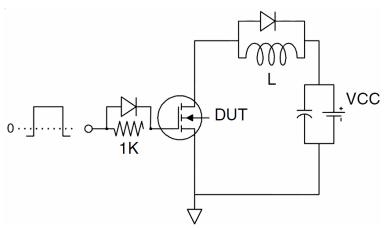
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Test Circuit

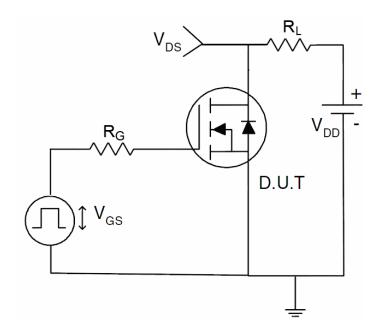
1) E_{AS} Test Circuit



2) Gate Charge Test Circuit



3) Switch Time Test Circuit





Typical Electrical and Thermal Characteristics (Curves)

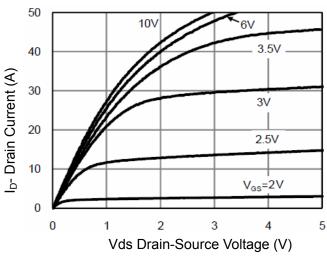


Figure 1 Output Characteristics

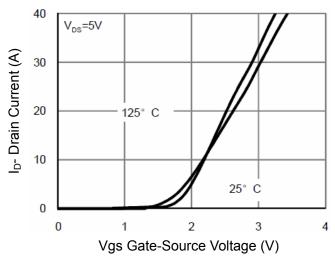


Figure 2 Transfer Characteristics

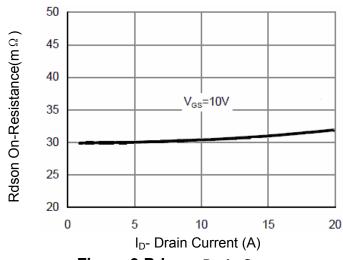


Figure 3 Rdson- Drain Current

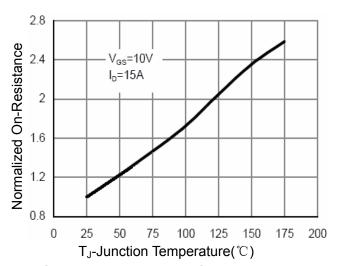


Figure 4 Rdson-JunctionTemperature

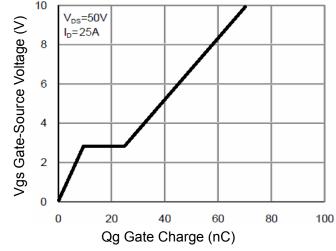


Figure 5 Gate Charge

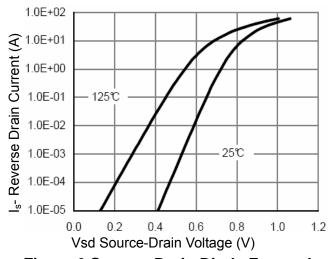


Figure 6 Source- Drain Diode Forward

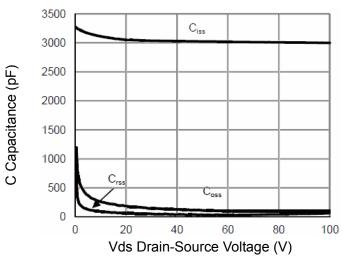


Figure 7 Capacitance vs Vds

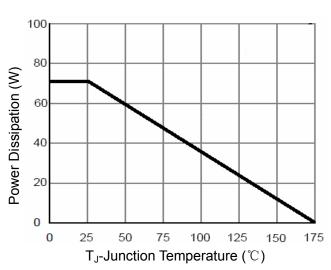


Figure 9 Power De-rating

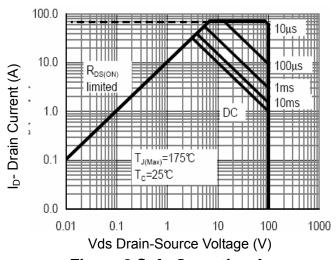


Figure 8 Safe Operation Area

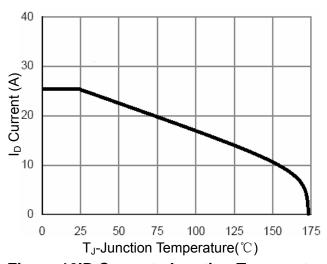


Figure 10ID Current- Junction Temperature

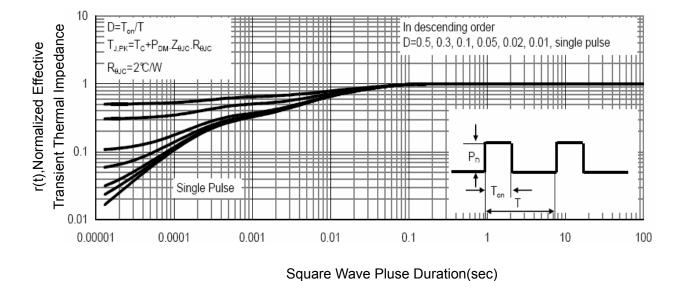
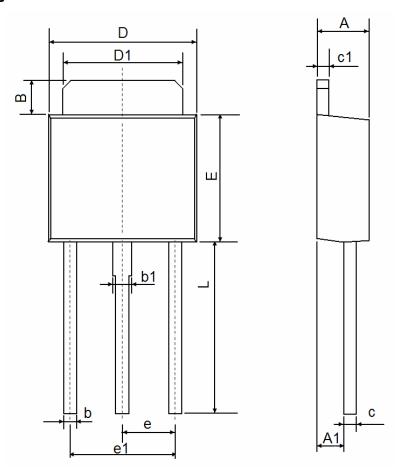


Figure 11 Normalized Maximum Transient Thermal Impedance

TO-251 Package Information



Ob. a.l.	Dimensions	In Millimeters	Dimensions In Inches		
Symbol	Min.	Max.	Min.	Max.	
А	2.200	2.400	0.087	0.094	
A1	1.050	1.350	0.042	0.054	
В	1.350	1.650	0.053	0.065	
b	0.500	0.700	0.020	0.028	
b1	0.700	0.900	0.028	0.035	
С	0.430	0.580	0.017	0.023	
c1	0.430	0.580	0.017	0.023	
D	6.350	6.650	0.250	0.262	
D1	5.200	5.400	0.205	0.213	
E	5.400	5.700	0.213	0.224	
е	2.300) TYP	0.091	TYP	
e1	4.500	4.700	0.177	0.185	
L	7.500	7.900	0.295	0.311	



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